



STF130N10F3, STH130N10F3-2, STP130N10F3

N-channel 100 V, 7.8 mΩ, 120 A STripFET™ Power MOSFET
in TO-220FP, H²PAK-2 and TO-220 packages

Datasheet — production data

Features

Order codes	V _{DSS}	R _{DS(on)} max.	I _D
STF130N10F3	100 V	9.6 mΩ	46 A
STH130N10F3-2		9.3 mΩ	120 A
STP130N10F3		9.6 mΩ	

- Ultra low on-resistance
- 100% avalanche tested

Applications

- High current switching applications

Description

These N-channel enhancement mode Power MOSFETs benefit from the latest refinement of STMicroelectronics' unique "single feature size" strip-based process, which decreases the critical alignment steps to offer exceptional manufacturing reproducibility. The result is a transistor with extremely high packing density for low on-resistance, rugged avalanche characteristics and low gate charge.

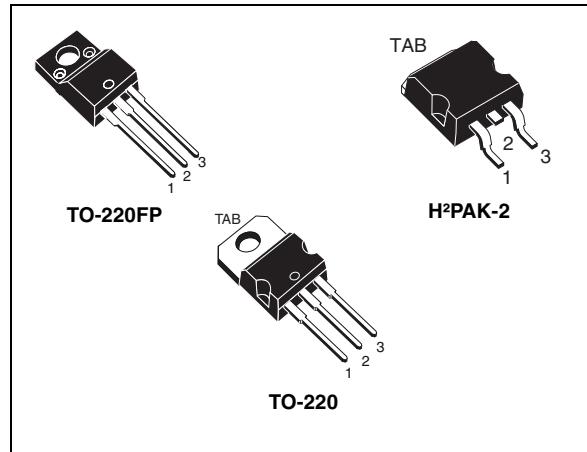
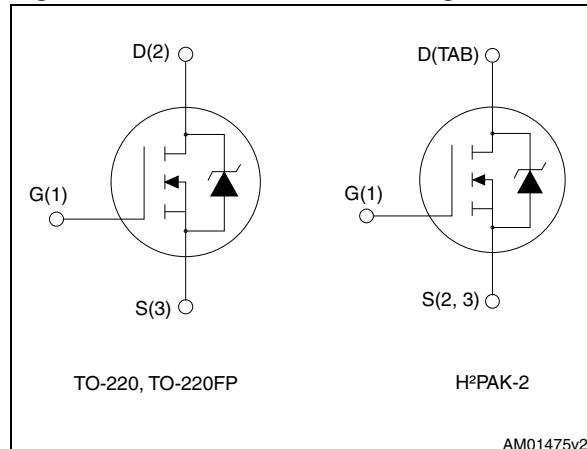


Figure 1. Internal schematic diagram



AM01475v2

Table 1. Device summary

Order codes	Marking	Package	Packaging
STF130N10F3	130N10F3	TO-220FP	Tube
STH130N10F3-2		H ² PAK-2	Tape and reel
STP130N10F3		TO-220	Tube

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics (curves)	5
3	Test circuits	9
4	Package mechanical data	10
5	Package mechanical data	18
6	Revision history	20

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value			Unit
		TO-220FP	H ² PAK-2	TO-220	
V _{DS}	Drain-source voltage	100			V
V _{GS}	Gate-source voltage	± 20			V
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25°C	46	120		A
I _D ⁽¹⁾	Drain current (continuous) at T _C =100°C	29	78		A
I _{DM} ⁽²⁾	Drain current (pulsed)	184	450		A
P _{TOT}	Total dissipation at T _C = 25°C	35	250		W
dv/dt	Peak diode recovery voltage slope	22			V/ns
E _{AS} ⁽³⁾	Single pulse avalanche energy	125			mJ
T _j T _{stg}	Operating junction temperature storage temperature	- 55 to 175			°C

1. Current limited by package.
2. Pulse width limited by safe operating area.
3. Starting T_j = 25 °C, I_D = 50 A, V_{DD} = 50 V for TO-220 and H²PAK-2; Starting T_j = 25 °C, I_D = 29 A, V_{DD} = 60 V for TO-220FP.

Table 3. Thermal data

Symbol	Parameter	Value			Unit
		TO-220FP	H ² PAK-2	TO-220	
R _{thj-case}	Thermal resistance junction-case	4.3	0.6	0.6	°C/W
R _{thj-a}	Thermal resistance junction-ambient	62.5		62.5	°C/W
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction-pcb		35		°C/W

1. When mounted on FR-4 board, on 1inch², 2oz Cu.

2 Electrical characteristics

($T_{CASE} = 25^\circ\text{C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0$, $I_D = 250 \mu\text{A}$	100	-		V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0$, $V_{DS} = 100 \text{ V}$ $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$		-	10 100	μA μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0$, $V_{GS} = \pm 20 \text{ V}$		-	± 200	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2	-	4	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}$, $I_D = 23 \text{ A}$ TO-220FP		8	9.6	$\text{m}\Omega$
		$V_{GS} = 10 \text{ V}$, $I_D = 60 \text{ A}$ H ² PAK TO-220		7.8 8	9.3 9.6	

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance			3305		pF
C_{oss}	Output capacitance	$V_{GS} = 0$, $V_{DS} = 25 \text{ V}$,	-	373	-	pF
C_{rss}	Reverse transfer capacitance	$f = 1 \text{ MHz}$		23		pF
Q_g	Total gate charge	$V_{DD} = 50 \text{ V}$, $I_D = 120 \text{ A}$,		57		nC
Q_{gs}	Gate-source charge	$V_{GS} = 10 \text{ V}$	-	22	-	nC
Q_{gd}	Gate-drain charge	(see Figure 20)		17		nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{on})}$	Turn-on delay time	$V_{DD} = 50 \text{ V}$, $I_D = 60 \text{ A}$		17		ns
t_r	Rise time	$R_G = 4.7 \Omega$		38		ns
$t_{d(\text{off})}$	Turn-off delay time	$V_{GS} = 10 \text{ V}$	-	52	-	ns
t_f	Fall time	(see Figure 19 , Figure 24)		7.2		ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}^{(1)}$	Source-drain current Source-drain current (pulsed)	For TO-220FP	-		46 184	A A
I_{SD} $I_{SDM}^{(2)}$	Source-drain current Source-drain current (pulsed)	For TO-220, H ² PAK-2	-		120 450	A A
$V_{SD}^{(3)}$	Forward on voltage	$I_{SD}=120\text{ A}, V_{GS}=0$; for TO-220, H ² PAK-2	-	1.5	V	
		$I_{SD}=46\text{ A}, V_{GS}=0$; for TO-220FP				
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD}=120\text{ A},$ $di/dt = 100\text{ A}/\mu\text{s},$ $V_{DD}=80\text{ V}, T_j=150\text{ }^\circ\text{C}$ (see <i>Figure 21</i>)	-	68 182 5.4		ns nC A

1. Pulse width limited by safe operating area
2. Pulse width limited by safe operating area
3. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220FP

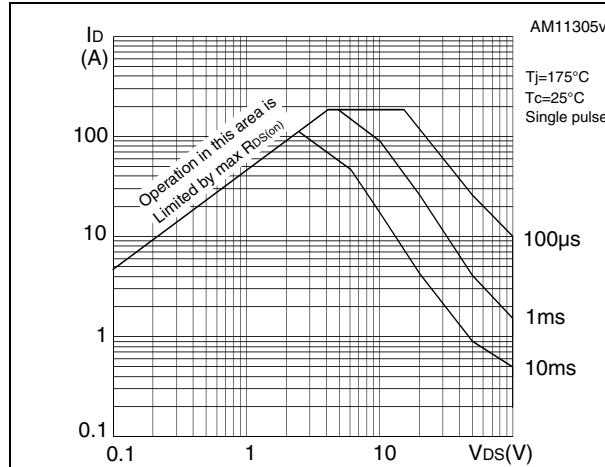


Figure 3. Thermal impedance for TO-220FP

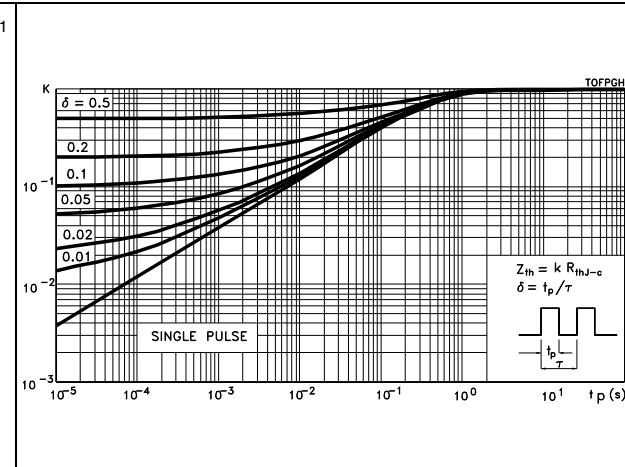
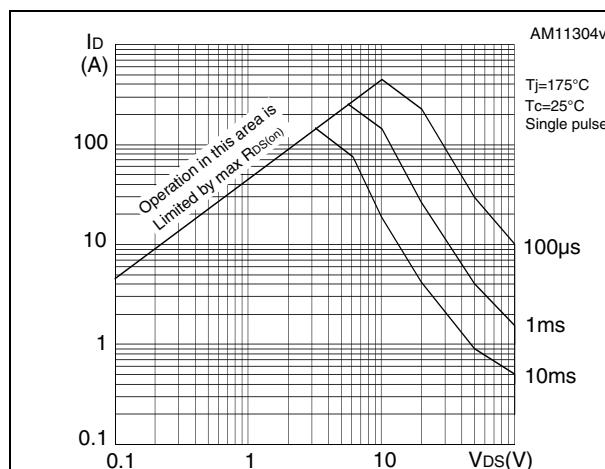
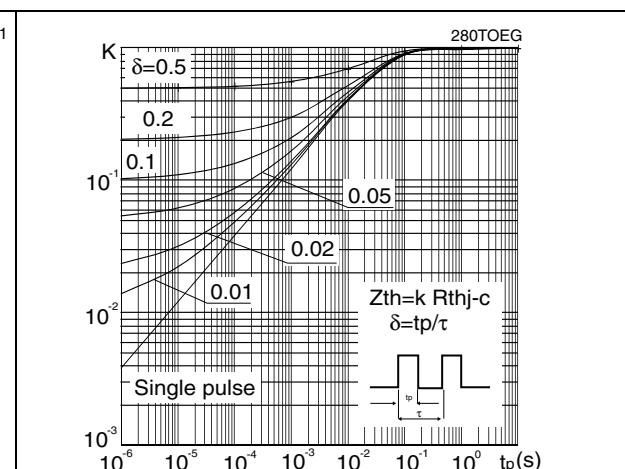
Figure 4. Safe operating area for H²PAK-2 and TO-220Figure 5. Thermal impedance for H²PAK-2 and TO-220

Figure 6. Output characteristics

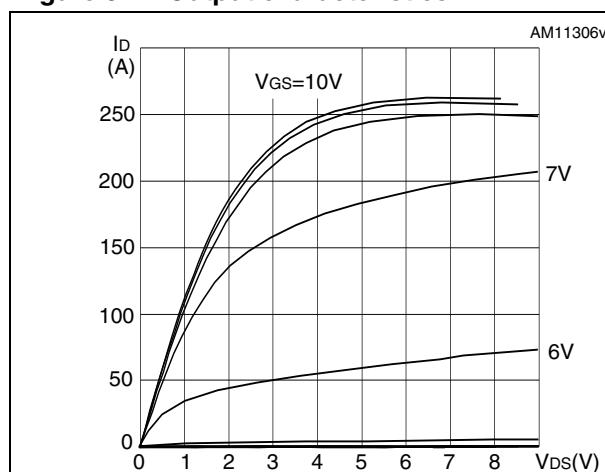


Figure 7. Transfer characteristics

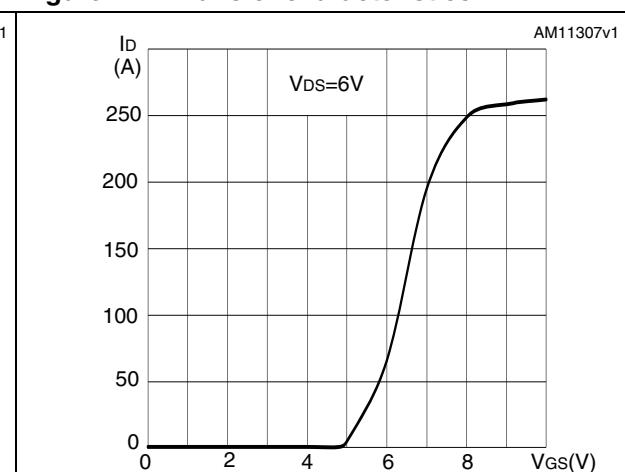


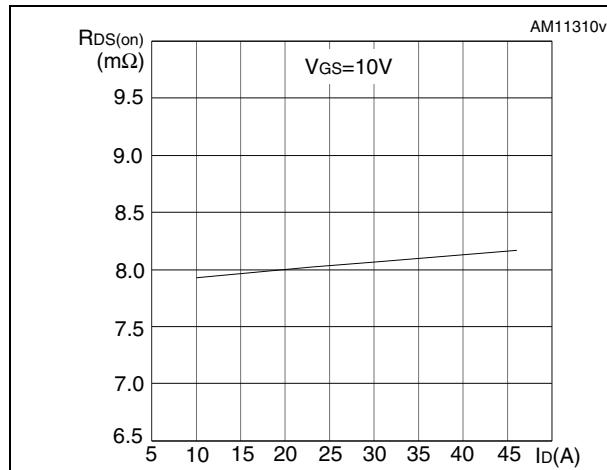
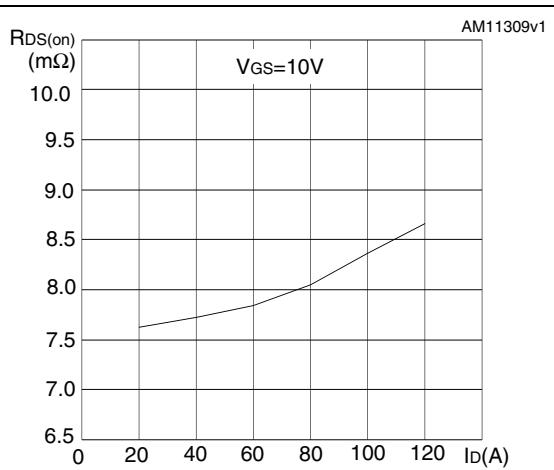
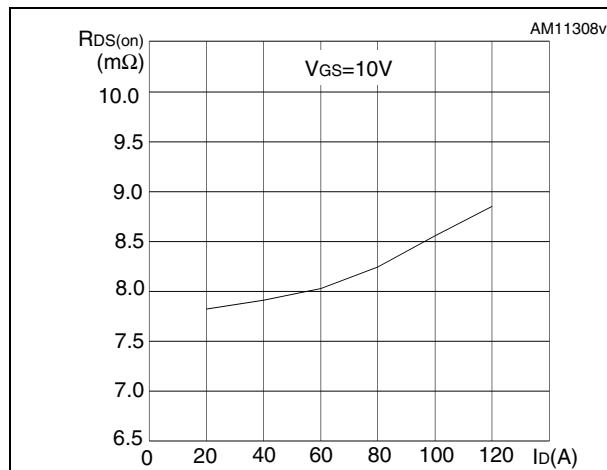
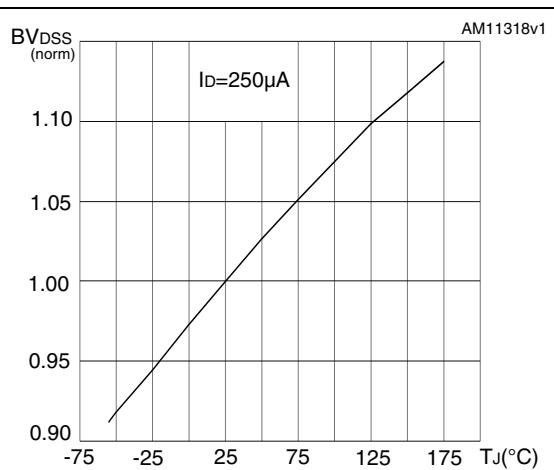
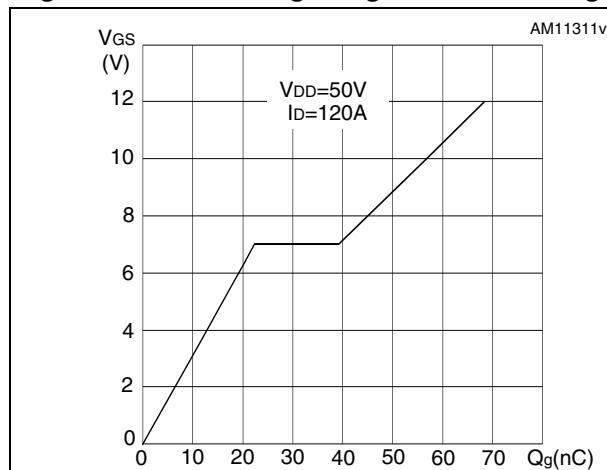
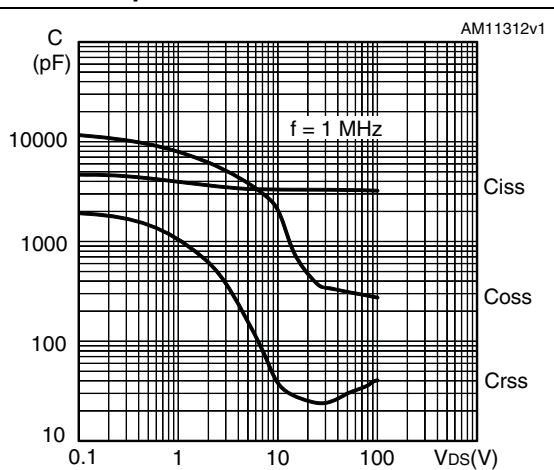
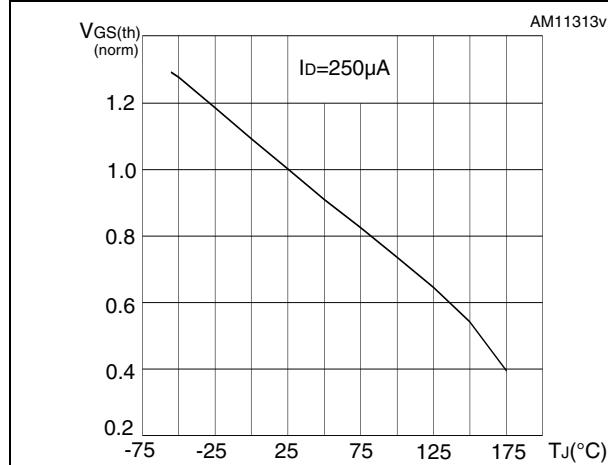
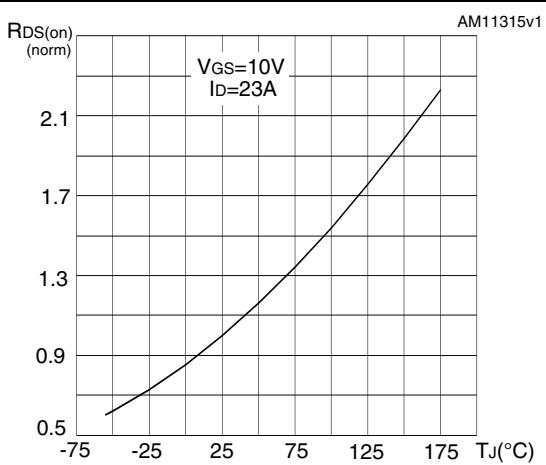
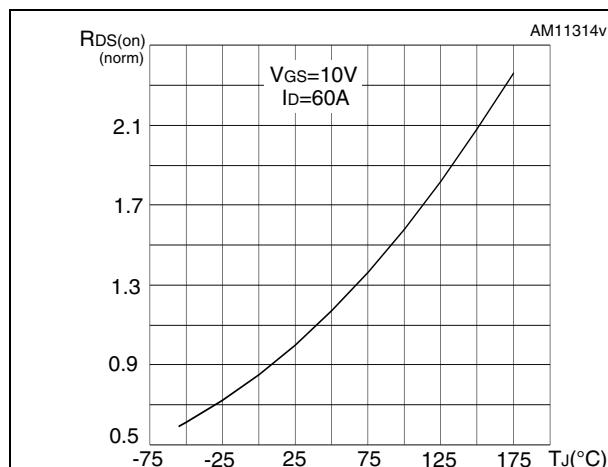
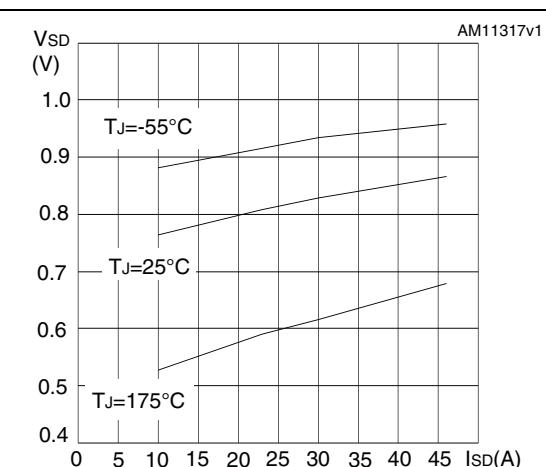
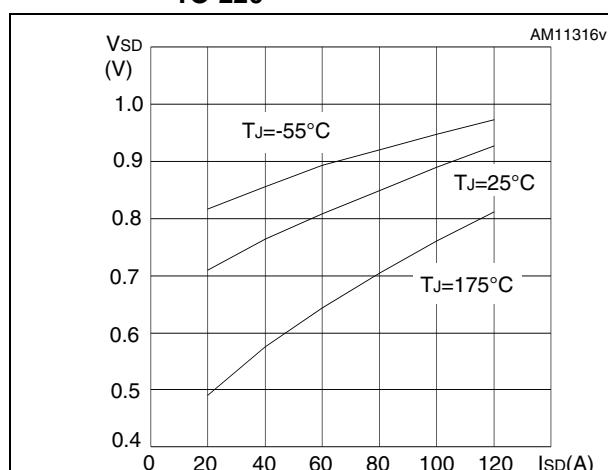
Figure 8. Static drain-source on-resistance for TO-220FP**Figure 9. Static drain-source on-resistance for H²PAK-2****Figure 10. Static drain-source on-resistance for TO-220****Figure 11. Normalized B_{VDSS} vs temperature****Figure 12. Gate charge vs gate-source voltage****Figure 13. Capacitance variations**

Figure 14. Normalized gate threshold voltage vs temperature**Figure 15. Normalized on resistance vs temperature for TO-220FP****Figure 16. Normalized on resistance vs temperature for H²PAK-2 and TO-220****Figure 17. Source-drain diode forward characteristics for TO-220FP****Figure 18. Source-drain diode forward characteristics for H²PAK-2 and TO-220**

3 Test circuits

Figure 19. Switching times test circuit for resistive load

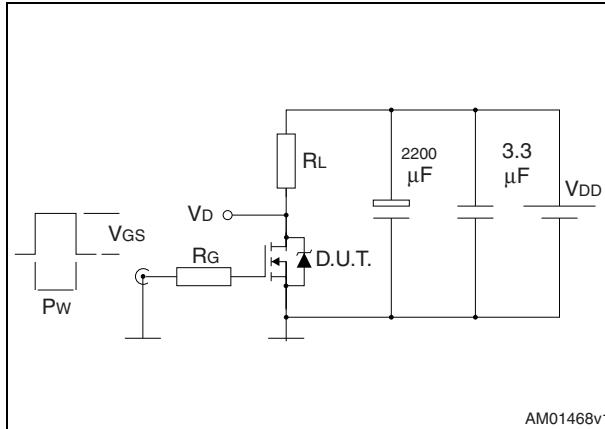


Figure 20. Gate charge test circuit

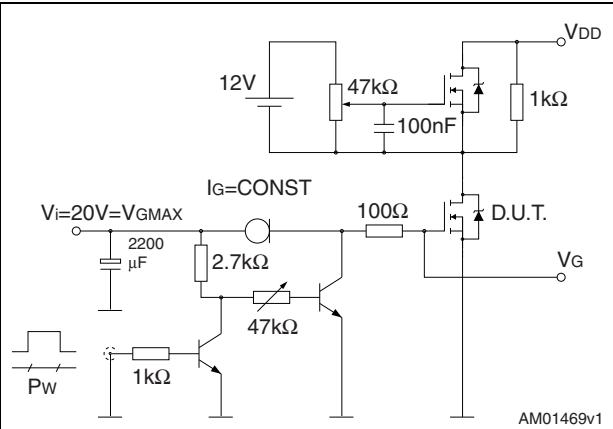


Figure 21. Test circuit for inductive load switching and diode recovery times

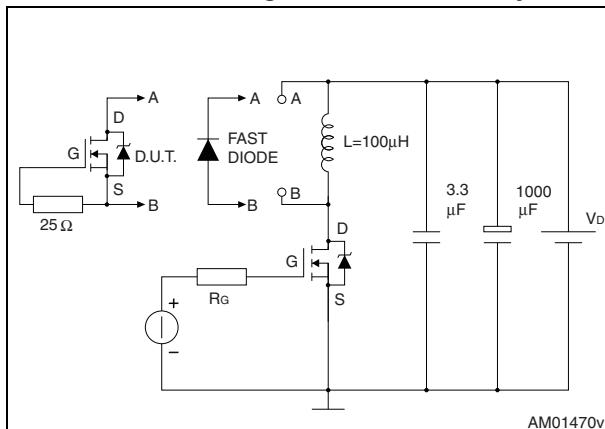


Figure 22. Unclamped inductive load test circuit

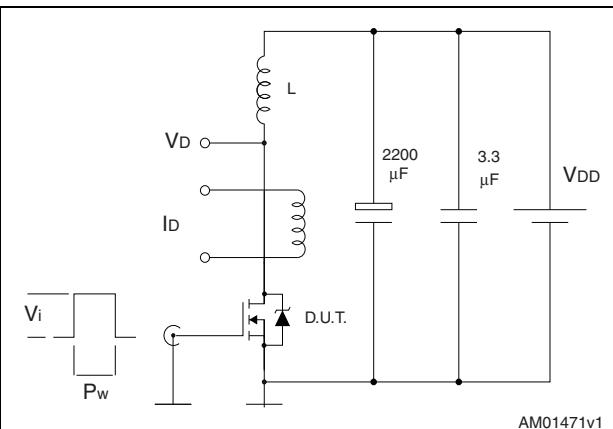


Figure 23. Unclamped inductive waveform

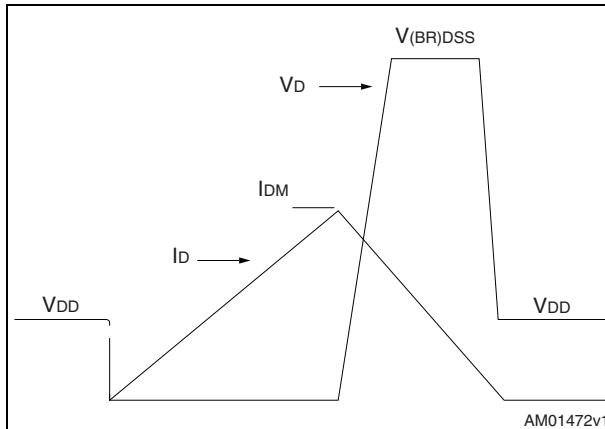
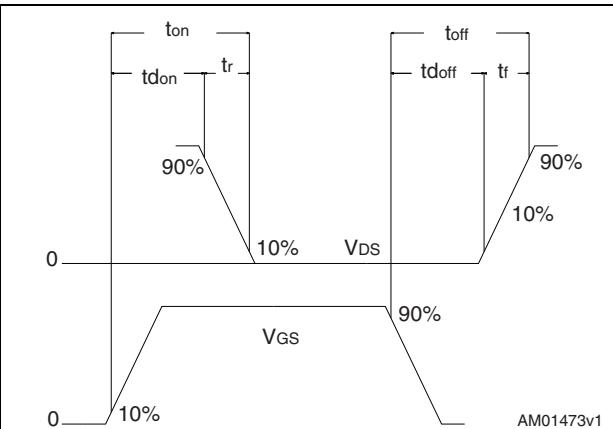


Figure 24. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

Figure 25. TO-220FP drawing

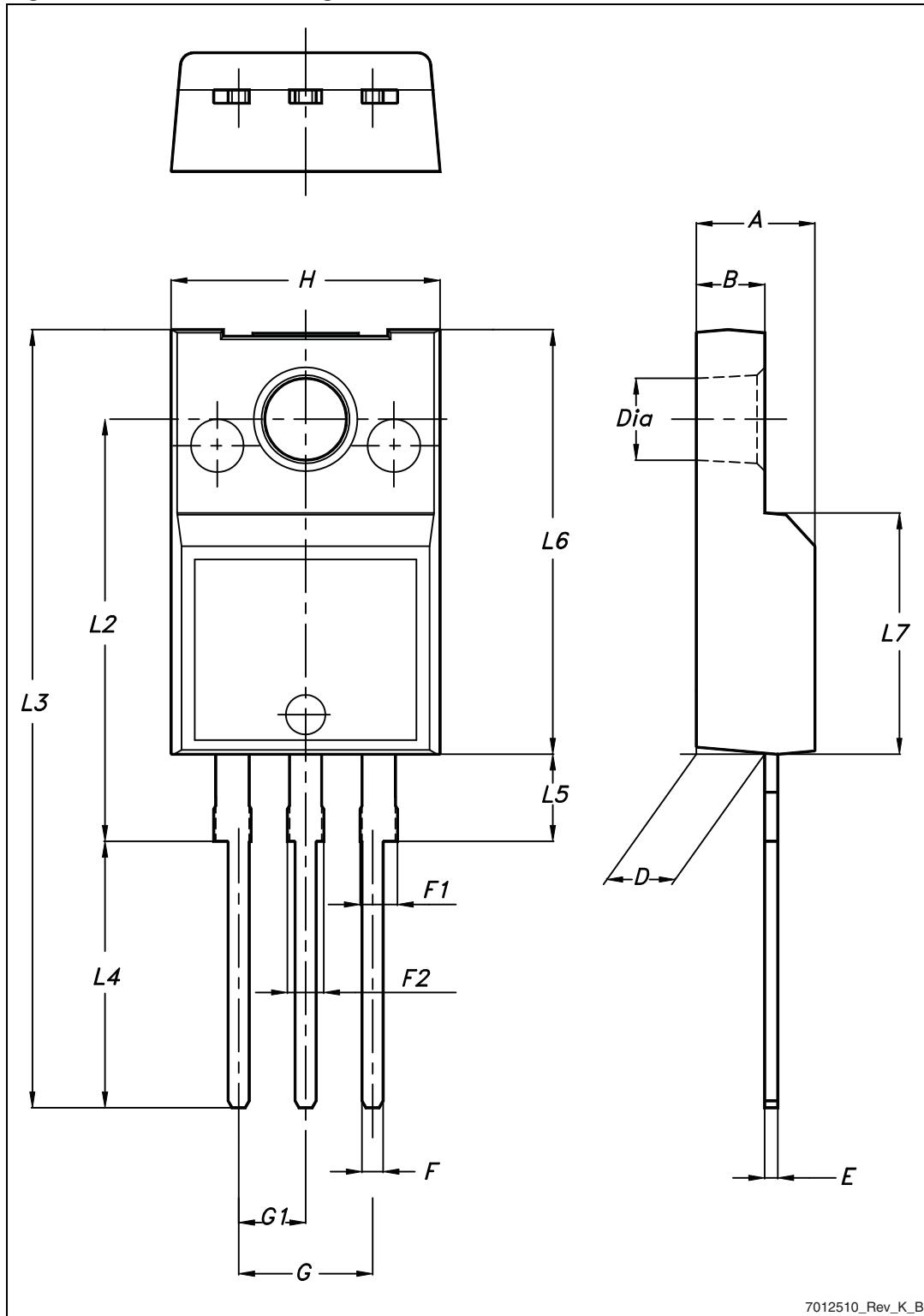


Table 9. H²PAK-2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.30		4.80
A1	0.03		0.20
C	1.17		1.37
e	4.98		5.18
E	0.50		0.90
F	0.78		0.85
H	10.00		10.40
H1	7.40		7.80
L	15.30		15.80
L1	1.27		1.40
L2	4.93		5.23
L3	6.85		7.25
L4	1.5		1.7
M	2.6		2.9
R	0.20		0.60
V	0°		8°

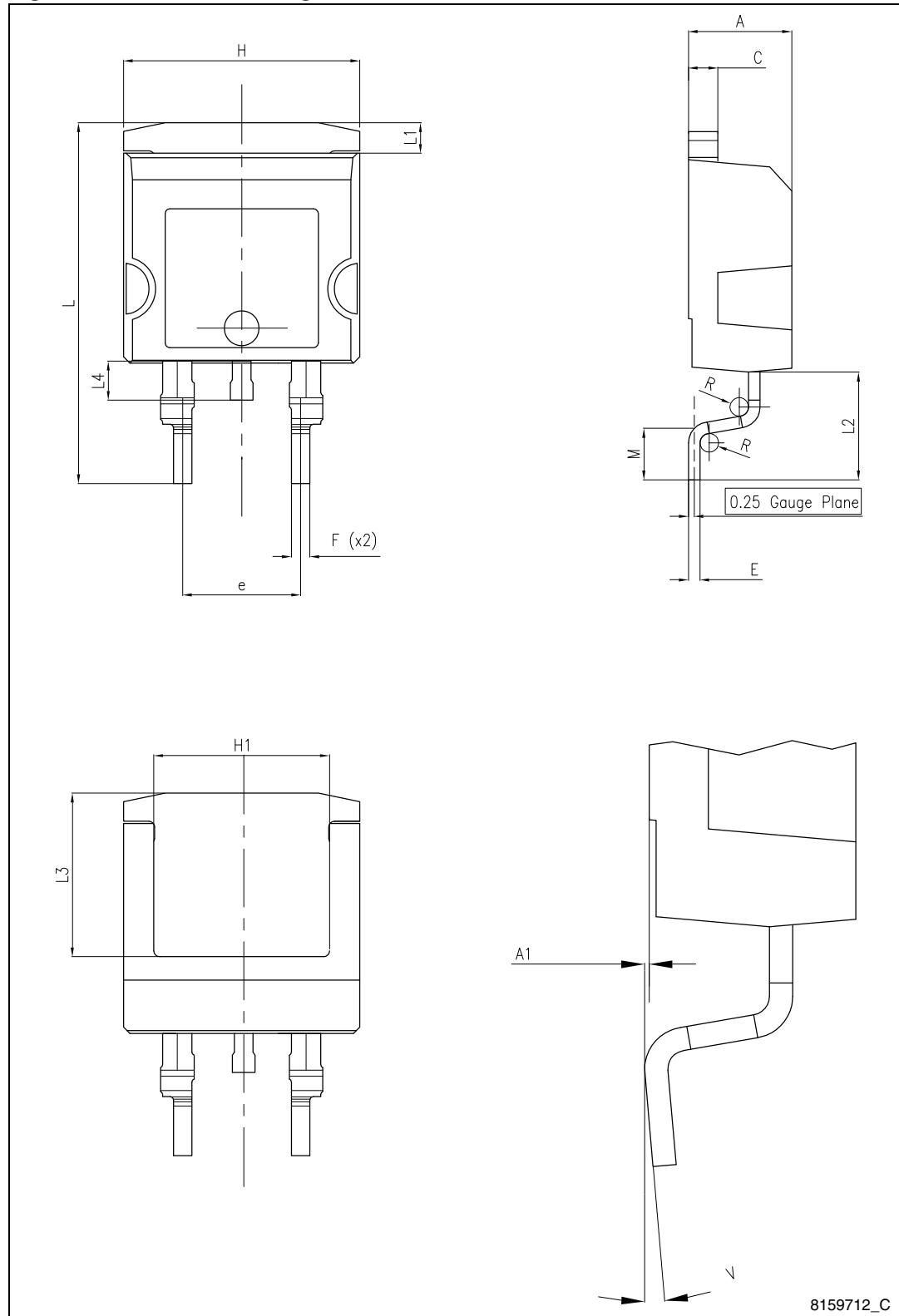
Figure 26. H²PAK-2 drawing

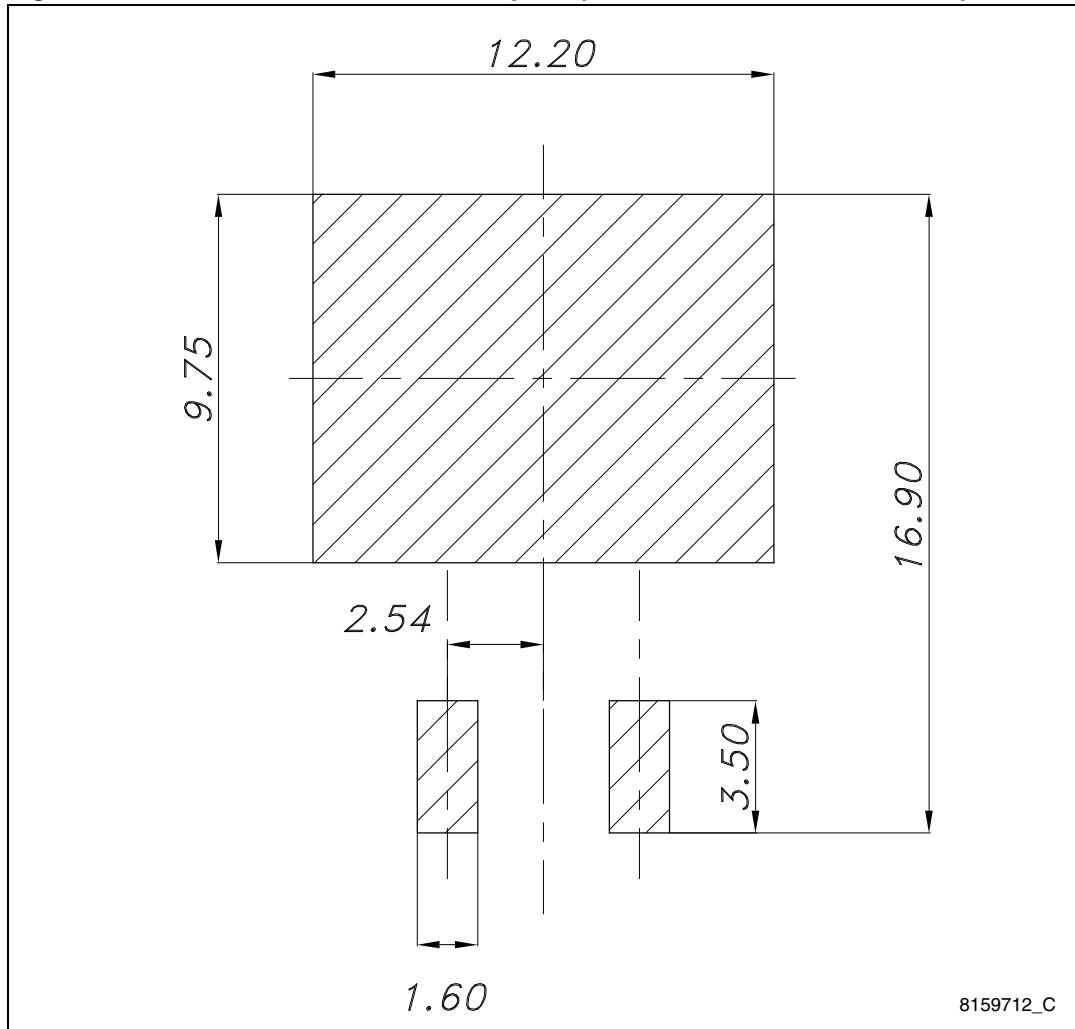
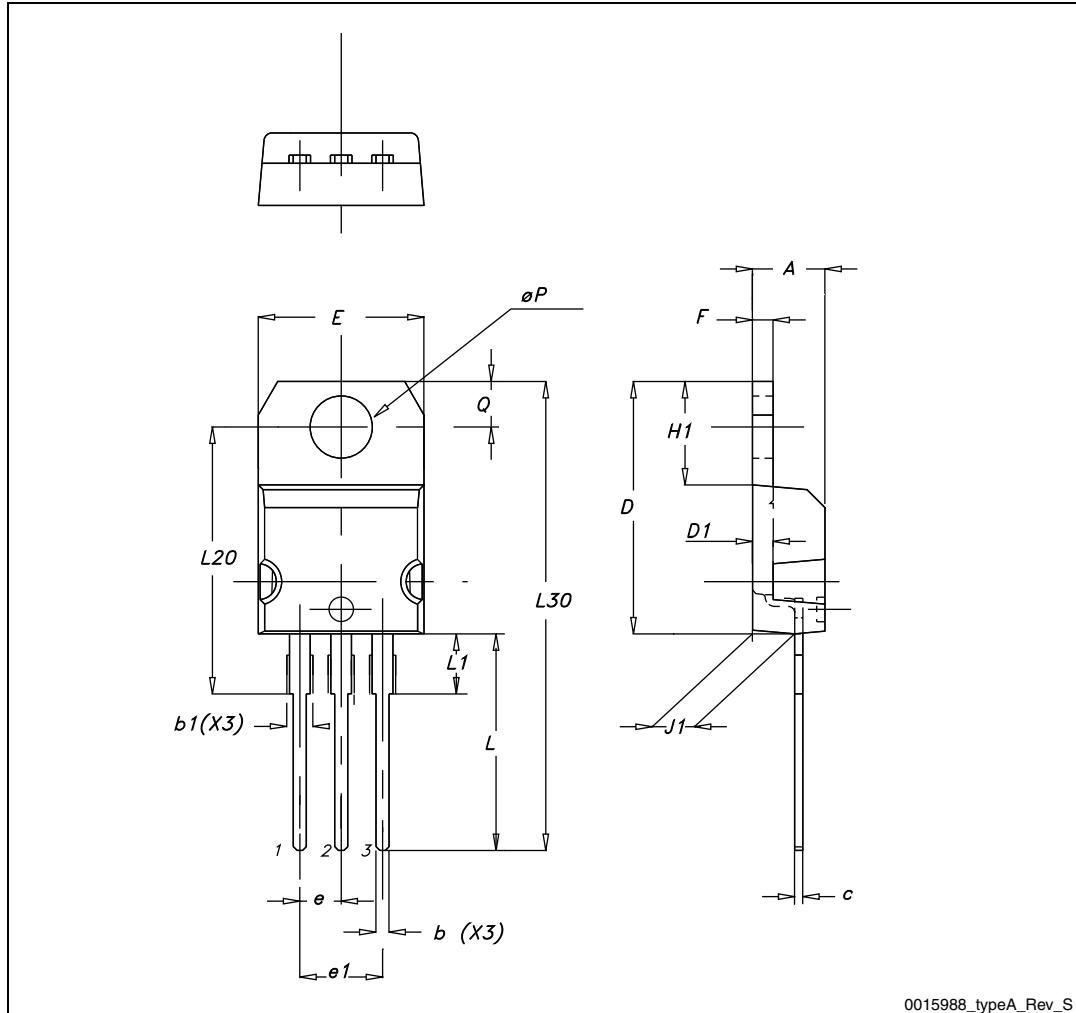
Figure 27. H²PAK-2 recommended footprint (dimensions are in millimeters)

Table 10. TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

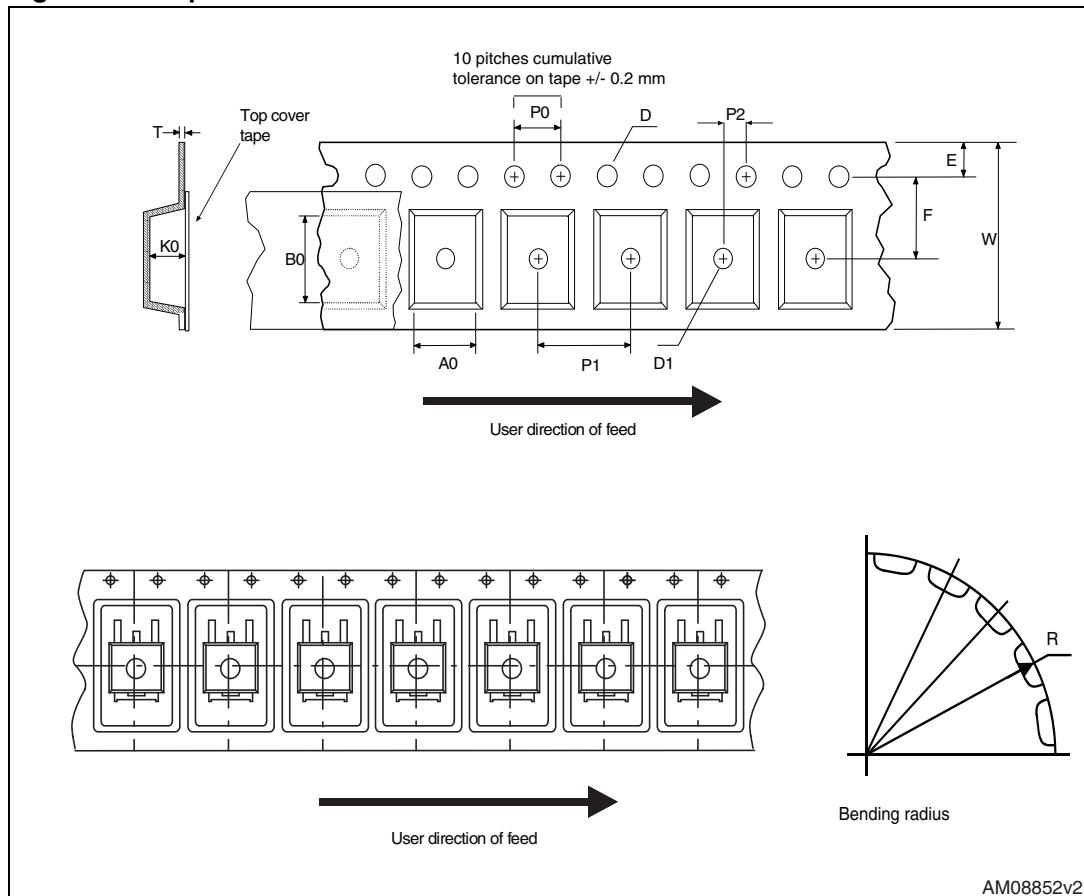
Figure 28. TO-220 type A drawing



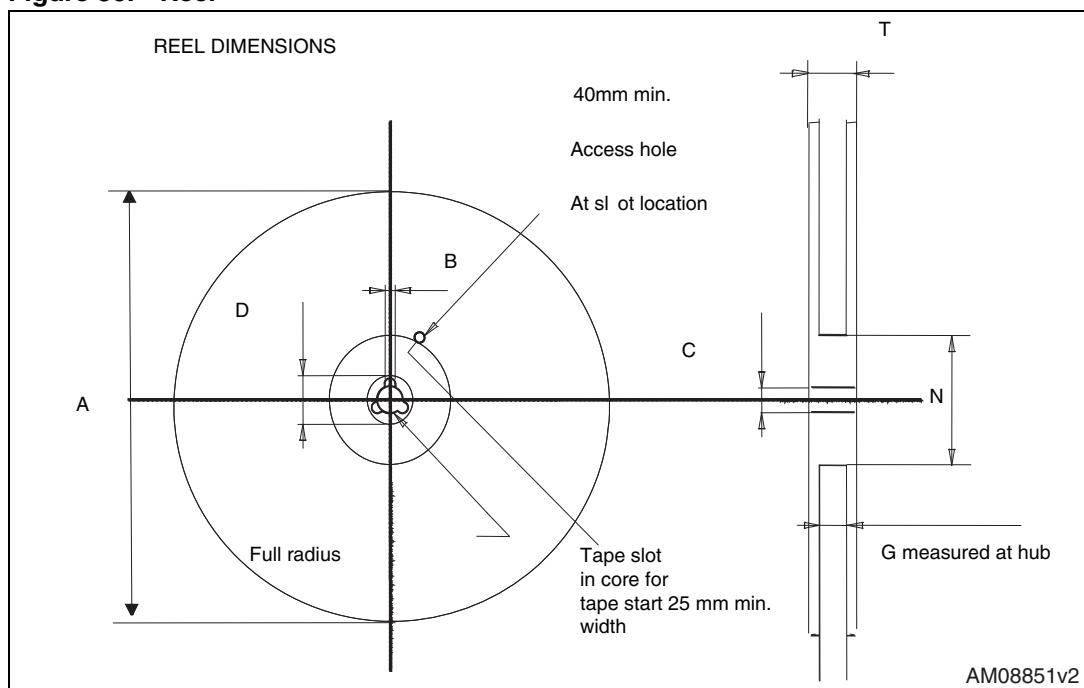
5 Package mechanical data

Table 11. H²PAK-2 tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty	1000
P2	1.9	2.1		Bulk qty	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Figure 29. Tape

AM08852v2

Figure 30. Reel

AM08851v2

6 Revision history

Table 12. Document revision history

Date	Revision	Changes
24-Feb-2011	1	First version.
07-May-2012	2	Added <i>Section 2.1: Electrical characteristics (curves)</i> . Minor text changes.

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